

**METHOD, APPARATUS, AND SYSTEM
FOR PHASE CHANGE MEMORY PACKAGING**

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ABSTRACT OF THE INVENTION

According to one embodiment, a die assembly is disclosed, comprising a package substrate and a plurality of stacked die on the package substrate, the plurality of stacked die including at least an uppermost die, a lowermost die, and at least one phase change memory die between the uppermost die and the lowermost die, wherein the uppermost die
10 and lowermost die are non-functional spacer die.

(Fig. 1)